# intel.

# 27C400 4M (256K x 16 or 512K x 8) CHMOS EPROM

- Word-Wide or Byte-Wide Configurable
- 4M 40-Pin Mask ROM Compatible — 40-Lead CERDIP Package
- Low Power Dissipation
  50 mA Max Active @ 5 MHz
  - 100 µA Max Standby

- **■** High Performance
  - 150 ns Maximum Access Time
  - $-V_{CC} = 5V \pm 10\%$
- **FAST Programming** 
  - Quick-Pulse Programming™ Algorithm
  - Programming as Fast as 28 Seconds

The Intel 27C400 is a 5V only 4,194,304 bit Erasable Programmable Read Only Memory, organized as 262,144 words of 16 bits each. A byte enable switch on pin 31 allows the device to be addressed as a 8 by 524,288 bit device. The 27C400 in pin-out and functionally compatible with 40-pin 4M Mask ROMs.

The 27C400 employs advanced CHMOS\* III-E circuitry for systems requiring low power, high speed performance and noise immunity.

The 27C400 is equally at home in both TTL or CMOS environments. Programming time is as fast as 28 seconds using Intel's Quick Pulse Programming Algorithm.

\*CHMOS is a patented process of Intel Corporation.

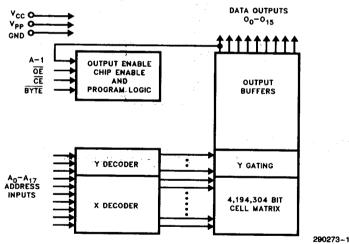


Figure 1. 27C400 Block Diagram

October 1991 Order Number: 290273-002

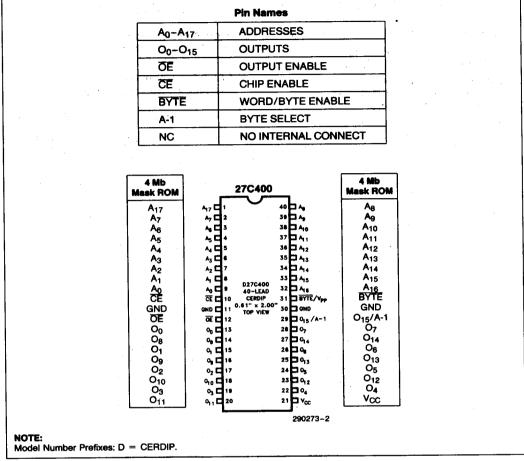


Figure 2. 27C400 Pin Configuration

#### **ABSOLUTE MAXIMUM RATINGS\***

Operating Temperature
Temperature under Bias 10°C to 80°C
Storage Temperature65°C to 125°C
Voltage on Any Pin (Except A <sub>9</sub> , V <sub>CC</sub> and BYTE/V <sub>PP</sub> ) with Respect to GND0.6V to 6.5V(2)
Voltage on A <sub>8</sub> , with Respect to GND 0.6V to 13V(2)
BYTE/V <sub>PP</sub> Supply Voltage with Respect to GND 0.6V to 14V(2)
V <sub>CC</sub> Supply Voltage

with Respect to GND . . . . . . . . . - 0.6V to 7V(2)

NOTICE: This data sheet contains preliminary information on new products in production. The specifications are subject to change without notice. Verify with your local Intel Sales office that you have the latest data sheet before finalizing a design.

\*WARNING: Stressing the device beyond the "Absolute Maximum Ratings" may cause permanent damage. These are stress ratings only. Operation beyond the "Operating Conditions" is not recommended and extended exposure beyond the "Operating Conditions" may affect device reliability.

### READ OPERATION DC CHARACTERISTICS(1) V<sub>CC</sub> = 5.0V ± 10%

Symbol	Parameter	Notes	Min	Тур	Max	Unit	Test Condition
ILI	Input Load Current	7		0.01	1.0	μΑ	V <sub>IN</sub> = 0V to V <sub>CC</sub>
lo	Output Leakage Current				±10	μΑ	V <sub>OUT</sub> = 0V to V <sub>CC</sub>
I <sub>SB</sub>	V <sub>CC</sub> Standby Current	5			1.0	mA	CE = V <sub>IH</sub>
			İ		100	μΑ	$\overline{CE} = V_{CC} \pm 0.2V$
lcc	V <sub>CC</sub> Operating Current	3			50	mA	f = 5 MHz, CE = V <sub>IL</sub> , I <sub>OUT</sub> = 0 mA
lpp	V <sub>PP</sub> Operating Current	3			10	μΑ	V <sub>PP</sub> = V <sub>CC</sub>
los	Output Short Circuit Current	4, 6			100	mA	
V <sub>IL</sub>	Input Low Voltage		-0.5		0.8	٧	
V <sub>IH</sub>	Input High Voltage		2.0		V <sub>CC</sub> + 0.5	٧	
VOL	Output Low Voltage				0.45	٧	I <sub>OL</sub> = 2.1 mA
V <sub>OH</sub>	Output High Voltage	-	2.4			٧	I <sub>OH</sub> = -400 μA

#### NOTES:

- 1. Operating temperature is for commercial product defined by this specification.
- 2. Minimum DC voltage is -0.5V on input/output pins. During transitions, this level may undershoot to -2.0V for periods <20 ns. Maximum DC voltage on input/output pins is V<sub>CC</sub> + 0.5V which, during transitions, may overshoot to V<sub>CC</sub> + 2.0V for periods <20 ns.
- Maximum active power usage is the sum Ipp + Icc. Maximum current value is with outputs O<sub>0</sub>-O<sub>15</sub> unloaded.
- 4. Output shorted for no more than one second. No more than one output shorted at a time.
- 5. BYTE/V<sub>PP</sub> =  $V_{CC} \pm 0.2V$  or GND  $\pm 0.2V$ . 6. Sampled, not 100% tested.
- 7. Typical limits are at  $V_{CC} = 5V$ ,  $T_A = 25$ °C.



### READ OPERATION AC CHARACTERISTICS(1) V<sub>CC</sub> = 5.0V ± 10%

Version	V <sub>CC</sub> ± 10%	27C400-1	150V10 <sup>(5)</sup>	27C400	Unit		
Symbol	Parameter	Notes	Min	Max	Min	Max	
tACC	Address to Output Delay			150		200	ns
t <sub>CE</sub>	CE to Output Delay	2		150		200	ns
toE	OE to Output Delay	2		60		70	ns
t <sub>DF</sub>	OE High to Output High Z	3		50		60	ns
<sup>t</sup> ОН	Output Hold from Addresses, CE or OE Change— Whichever Occurs First	3	0		0		ns

#### NOTES:

1. See AC Input/Output Reference Waveform for timing measurements.

2. OE may be delayed up to t<sub>CE</sub>-t<sub>OE</sub> after the falling edge of CE without impact on t<sub>CE</sub>.

3. Sampled, not 100% tested.

voltages.

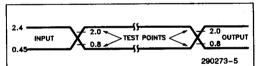
4. Includes O<sub>15</sub>/A-1.

5. Both byte- and word-wide-read mode are available with the 27C400-200V10. 27C400-150V10 specs are valid only in word-wide-read mode operation.

#### CAPACITANCE(3) TA = 25°C, f = 1 MHz

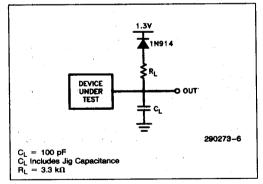
Symbol	Parameter	Typical	Max	Unit	Condition
C <sub>IN</sub>	Input Capacitance	4	8	pF	V <sub>IN</sub> = 0V
C <sub>OUT</sub>	Output Capacitance(4)	8	12	pF	V <sub>OUT</sub> = 0V
C <sub>VPP</sub>	V <sub>PP</sub> Capacitance	18	25	pF	$V_{PP} = 0V$

#### AC INPUT/OUTPUT REFERENCE WAVEFORM



AC test inputs are driven at V<sub>OH</sub> (2.4 V<sub>TTL</sub>) for a Logic "1" and V<sub>OL</sub> (0.45 V<sub>TTL</sub>) for a Logic "0". Input timing begins at V<sub>IH</sub> (2.0 V<sub>TTL</sub>) and V<sub>IL</sub> (0.8 V<sub>TTL</sub>). Output timing ends at V<sub>IH</sub> and V<sub>IL</sub>. Input rise and fall times (10% to 90%)  $\leq$  10 ns.

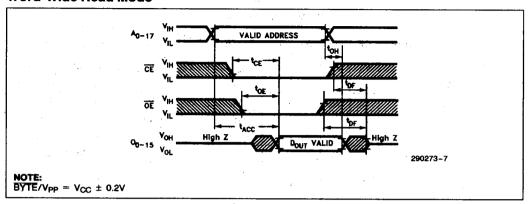
#### AC TESTING LOAD CIRCUIT



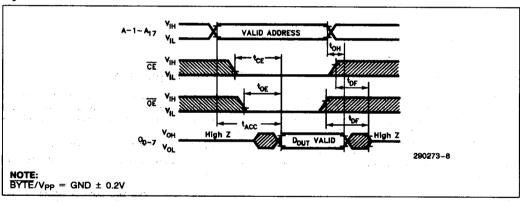


#### **AC WAVEFORMS**

# Word-Wide Read Mode



### **Byte-Wide Read Mode**



#### **DEVICE OPERATION**

The Mode Selection table lists 27C400 operating modes. Read Mode requires a single 5V power supply. All inputs, except V<sub>CC</sub> and BYTE/V<sub>PP</sub>, and A<sub>9</sub> during inteligent Identifier™ Mode, are TTL or CMQS.

**Table 1. Mode Selection** 

Mode	Notes	ČE	ŌĔ	A9	A <sub>0</sub>	O <sub>15</sub> /A-1	BYTE/ V <sub>PP</sub> (4)	Vcc	O <sub>8-14</sub>	0 <sub>0-7</sub>
Read (Word)	1	VIL	VIL	Х	X	D <sub>15</sub> Out	Vcc	Vcc	D <sub>8-14</sub> Out	D <sub>0-7</sub> Out
Read (Upper Byte)		VIL	V <sub>IL</sub>	Х	X	VIH	GND	V <sub>CC</sub>	High Z	D <sub>8-15</sub> Out
Read (Lower Byte)		VIL	V <sub>IL</sub>	Х	×	V <sub>IL</sub>	GND	Vcc	High Z	D <sub>0-7</sub> Out
Output Disable		VIL	V <sub>IH</sub>	Х	X	High Z	X	Vcc	High Z	High Z
Standby		ViH	×	X	X	High Z	х	Vcc	High Z	High Z
Program	2	VIL	V <sub>IH</sub>	Х	X	D <sub>15</sub> In	V <sub>PP</sub>	V <sub>CP</sub>	D <sub>8-14</sub> In	D <sub>0-7</sub> In
Program Verify		VIH	VIL	х	Х	D <sub>15</sub> Out	V <sub>PP</sub>	V <sub>CP</sub>	D <sub>8-14</sub> Out	D <sub>0-7</sub> Out
Program Inhibit		VIH	V <sub>IH</sub>	х	Х	High Z	V <sub>PP</sub>	V <sub>CP</sub>	High Z	High Z
inteligent Identifier	2, 3	VIL	VIL	V <sub>ID</sub>	V <sub>IL</sub>	0B	Vcc	Vcc	ООН	89H
—Manufacturer —Device		V <sub>IL</sub>	VIL	V <sub>iD</sub>	V <sub>IH</sub>	0B	Vcc	Vcc	44H	EFH

#### NOTES:

- 1. X can be  $V_{IL}$  or  $V_{IH}$ . For  $\overline{BTTL}/V_{PP}$ , X = GND or  $V_{CC}$ .
- 2. See DC Programming Characteristics for VCP, Vpp and VID voltages.
- 3. A1-A8, A10-A17 = VIL.
- 4. BYTE/VPP is intended for operation under DC Voltage conditions only.

#### **Read Mode**

The 27C400 has two control functions; both must be enabled to obtain data at the outputs.  $\overline{CE}$  is the power control and device select.  $\overline{OE}$  controls the output buffers to gate data to the outputs. With addresses stable, the address access time ( $t_{ACC}$ ) equals the delay from  $\overline{CE}$  to output ( $t_{CE}$ ). Outputs display valid data  $t_{OE}$  after  $\overline{OE}$ 's falling edge, assuming  $t_{ACC}$  and  $t_{CE}$  times are met.

#### **Word-Wide Mode**

With  $\overline{\text{BYTE}}/\text{V}_{PP}$  at  $\text{V}_{CC} \pm 0.2\text{V}$  outputs  $\text{O}_{0-7}$  present data  $\text{D}_{0-7}$  and outputs  $\text{O}_{8-15}$  present data  $\text{D}_{8-15}$ , after  $\overline{\text{CE}}$  and  $\overline{\text{OE}}$  are appropriately enabled.

#### **Byte-Wide Mode**

With  $\overline{\text{BYTE}}/\text{Vpp}$  at GND  $\pm$  0.2V, outputs  $O_{8-14}$  are tri-stated. If  $O_{15}/\text{A-1} = V_{\text{IH}}$ , outputs  $O_{0-7}$  present data bits  $D_{8-15}$ . If  $O_{15}/\text{A-1} = V_{\text{IL}}$ , outputs  $O_{0-7}$  present data bits  $D_{0-7}$ .

Read Operation AC Characteristic specifications are currently valid in byte-wide mode only when using the 27C400-200V10. Please contact your local Intel sales office for additional information.

#### **Two Line Output Control**

EPROMs are often used in larger memory arrays. Intel provides two control inputs to accommodate multiple memory connections. Two-line control provides for:

- a. lowest possible memory power dissipation
- complete assurance that data bus contention will not occur

To efficiently use these two control inputs, an address decoder should enable  $\overline{CE}$  while  $\overline{OE}$  should be connected to all memory devices and the system's  $\overline{READ}$  control line. This assures that only selected memory devices have active outputs while deselected memory devices are in Standby Mode.

#### Standby Mode

Standby Mode substantially reduces  $V_{CC}$  current. When  $CE = V_{IH}$ , outputs are in a high impedance state, independent of  $\overline{OE}$ .

#### **Program Mode**

# Caution: Exceeding 14V on $\overline{\text{BYTE}}/\text{V}_{PP}$ will permanently damage the device.

Initially, and after each erasure, all EPROM bits are in the "1" state. Data is introduced by selectively programming "0s" into the desired bit locations. Although only "0s" are programmed the data word can contain both "1s" and "0s". Ultraviolet light erasure is the only way to change "0s" to "1s".

Program Mode is entered when  $\overline{\text{BYTE}}/\text{Vpp}$  is raised to 12.75V. Data is introduced by applying a 16-bit word to the output pins. Pulsing  $\overline{\text{CE}}$  low while  $\overline{\text{OE}} = V_{\text{IH}}$  programs that data into the device.

#### **Program Verify**

A verify should be performed following a program operation to determine that bits have been correctly programmed. With  $V_{CC}$  at 6.25V, a substantial program margin is ensured, The verify is performed with  $\overline{CE}$  at  $V_{IH}$ . Valid data is available on  $O_{0-15}$   $V_{CE}$  after  $\overline{OE}$  falls low.

#### Program Inhibit

Program Inhibit mode allows parallel programming of multiple EPROMs with different data. CE-high inhibits programming of non-targeted devices. Except for CE and OE, parallel EPROMs may have common inputs.

## inteligent Identifier™ Mode

The inteligent Identifier Mode will determine an EPROM's manufacturer and device type, allowing programming equipment to automatically match a device with its proper programming algorithm.

This mode is activated when a programmer forces  $12V \pm 0.5V$  on  $A_9$ . With  $\overline{CE}$ ,  $\overline{OE}$ ,  $A_1-A_8$ , and  $A_{10}-A_{17}=V_{IL}$ ,  $A_0=V_{IL}$  will present the manufacturer's code and  $A_0=V_{IH}$  the device code. This mode functions in the  $25^{\circ}C$   $\pm 5^{\circ}C$  ambient temperature range required during programming.

#### SYSTEM CONSIDERATIONS

EPROM power switching characteristics require careful device decoupling. System designers are interested in three supply current issues-standby currents levels (ISB), active current levels (ICC), and transient current peaks produced by falling and rising edges of CE. Transient current magnitudes depend on the device outputs' capacitive and inductive loading. Two-Line Control and proper decoupling capacitor selection will suppress transient voltage peaks. Each device should have a 0.1 µF ceramic capacitor connected between its V<sub>CC</sub> and GND. This high frequency, low inherent-inductance capacitor should be placed as close as possible to the device. Additionally, for every eight devices, a 4.7 µF electrolytic capacitor should be placed at the array's power supply connection between V<sub>CC</sub> and GND. The bulk capacitor will overcome voltage slumps caused by PC board trace inductances.

#### **ERASURE CHARACTERISTICS**

Erasure begins when EPROMs are exposed to light with wavelengths shorter than approximately 4000 Angstroms (Å). It should be noted that sunlight and certain fluorescent lamps have wavelengths in the 3000–4000Å range. Data shows that constant exposure to room level fluorescent lighting can erase an EPROM in approximately 3 years, while it takes approximately 1 week when exposed to direct sunlight. It the device is exposed to these lighting conditions for extended periods, opaque labels should be placed over the window to prevent unintentional erasure.

The recommended erasure procedure is exposure to ultraviolet light of wavelengths 2537Å. The intergrated dose (UV intensity × exposure time) for erasure should be a minimum of 15 Wsec/cm². Erasure time is approximately 15 to 20 minutes using an ultraviolet lamp with a 12000 μW/cm² power rating. The EPROM should be placed within 1 inch of the lamp tubes. An EPROM can be permanently damaged if the integrated dose exceeds 7258 Wsec/cm² (1 week @ 12000 μW/cm²).

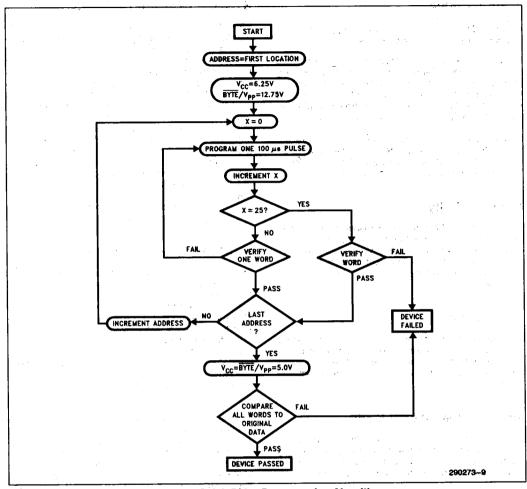


Figure 3. Quick-Pulse Programming Algorithm

# Quick-Pulse Programming™ Algorithm

The Quick-Pulse Programming™ algorithm programs Intel's 27C400. Developed to substantially reduce programming throughput, this algorithm can program the 27C400 as fast as 28 seconds. Actual programming time depends on programmer overhead.

The Quick-Pulse Programming algorithm employs a 100  $\mu s$  pulse followed by a word verification to

determine when the addressed word has been successfully programmed. The algorithm terminates if 25 attempts fail to program a word.

The entire program-pulse/word-verify sequence is performed with  $\overline{BYTE}/V_{PP}=12.75V$  and  $V_{CC}=6.25V$ . When programming is complete, all words are compared to the original data with  $V_{CC}=\overline{BYTE}/V_{PP}=5.0V$ .

# DC PROGRAMMING CHARACTERISTICS $T_A = 25^{\circ}C \pm 5^{\circ}C$

Symbol	Parameter	Notes	Min	Тур	Max	Unit	Test Conditions
ILI	Input Load Current		-		1	μΑ	$V_{IN} = V_{IL} \text{ or } V_{IH}$
ICP	V <sub>CP</sub> Program Current	1			50	mA	CE = VIL
lpp	V <sub>PP</sub> Program Current	1			50	mA	CE = VIL
V <sub>IL</sub>	Input Low Voltage		-0.1		0.8	٧	
VIH	Input High Voltage		2.4		6.5	٧	
VOL	Output Low Voltage (Verify)			,	0.45	٧	I <sub>OL</sub> = 2.1 mA
V <sub>OH</sub>	Output High Voltage (Verify)		3.5			٧	$I_{OH} = -2.5  \text{mA}$
V <sub>ID</sub>	A <sub>9</sub> inteligent Identifer Voltage		11.5	12.0	12.5	٧	
V <sub>PP</sub>	V <sub>PP</sub> Program Voltage	2, 3	12.5	12.75	13.0	٧	
V <sub>CP</sub>	V <sub>CC</sub> Supply Voltage (Program)	2	6.0	6.25	6.5	V	

### AC PROGRAMMING CHARACTERISTICS(4) $T_A = 25^{\circ}C \pm 5^{\circ}C$

Symbol	Parameter	Notes	Min	Тур	Max	Unit
tvcs	V <sub>CP</sub> Setup Time	2	2			μs
typs	V <sub>PP</sub> Setup Time	2	2			μs
tas	Address Setup Time		2			μs
t <sub>DS</sub>	Data Setup Time	-	2			μs
t <sub>PW</sub>	CE Program Pulse Width		95	100	105	μs
t <sub>DH</sub>	Data Hold Time		2			μs
toes	OE Setup Time		2			μs
t <sub>OE</sub>	Data Valid from OE	5			150	ns
t <sub>DFP</sub>	OE High to Output High Z	5, 6	0		130	ns
t <sub>AH</sub>	Address Hold Time		0			μs

#### NOTES:

- 1. Maximum current is with outputs  $O_0$ - $O_{15}$  unloaded.
- V<sub>CP</sub> must be applied simultaneously or before V<sub>PP</sub> and removed simultaneously or after V<sub>PP</sub>.
   When programming, a 0.1 μF capacitor is required between V<sub>PP</sub> and GND to suppress spurious voltage transients, which can damage the device.
- 4. See AC Input/Output Reference Waveform for timing measurements.
- 5.  $t_{OE}$  and  $t_{DFP}$  are device characteristics but must be accommodated by the programmer. 6. Sampled, not 100% tested.



#### PROGRAMMING WAVEFORMS

